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U.S. PATENT DOCUMENTS											
EXAMINER INITIAL		DOCUMENT	DATE		NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)			
Mbe	AA	5,563,762	10/1996	Leung et al		i-					
	AB	5,117,272	05-1992	Nomura et al							
	AC	5,310,863	05-1994	Sachdev							
	AD	6,071,755	06-2000	Baba et al							
	AE	6,106,906	0B-2000	Matsuda et al							
	AF	5,296,716	03-1994	Ovashinsky et	al						
	AG	4,132,823	1/2/79	Blackwell et	al						
Noe	АН	6,465,827	10/2002	Tanaka et al	·						
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				FOREIGN PATE	NT DOCUMENTS						
		DOCUMENT	DATE	COUNTRY		CLASS	SUBCLASS	TRANSLATION YES NO			
Mba	AL	8-124917	05-1996	Japan		<u> </u>					
70	ΑM	7-278301	10-1995	Japan							
(V_	AN	07-221259	B/18/95	Japan							
Mbc	AC	09-293837	11/11/97	Japan							
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			OTHER DOCU	MENTS (Including A	uthor, Title, Date, Pertinent P	ages, etc	:.) 				
1		Lecture Collections in '96 Ferroelectric Film Memory Technique Forum,									
Mpc	AF	Science	Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.								
	_	Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins,									
No	AS	Vol. 1	3, No. 4,	page 37, right	olumn, lines 8-23,	Ogata	et al, 199	2.			
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nbe	ГА	Packag Its Re	Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.								
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		(	OTHER DOCUMEN	NTS (Including A	uthor, Title, Date, Pertiner	nt Pages,	etc.)					
Mbe	AR		A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.									
Mpe	AS	Reliabi	Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al.									
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EXAMINER		Jasmine	clark		DATE CONSIDERED	7/21	04					
		ial if reference considere			P 609; Draw line through citation if no	t in conforman		t considered. Includ	a copy of thi	s form with		
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